

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Chee Kiang Yew, et al.

Art Unit (parent case): 2812

Serial No.: TBD

Examiner (parent case): Lattin, C.W.

Filed: Herewith

Docket: TI-26239.1

For: Direct Attachment of Semiconductor
Chip to Organic Substrate

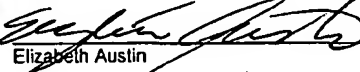
Conf. No.: TBD

PRELIMINARY AMENDMENT

Commissioner For Patents
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that on or before this date the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner For Patents, Alexandria, VA 22313-1450.


Elizabeth Austin

7/2/2003
Date

Sir:

Please enter the following amendment prior to examination of the instant application.

In the Specification:

Please amend the specification by inserting before the first line the sentence:

-- This is a divisional application of Serial No. 09/401,572, filed 09/22/1999, --

, U.S. Patent No. 6,602,803.